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(54) Title: POLISHING PAD WITH MULTI-MODAL DISTRIBUTION OF PORE DIAMETERS

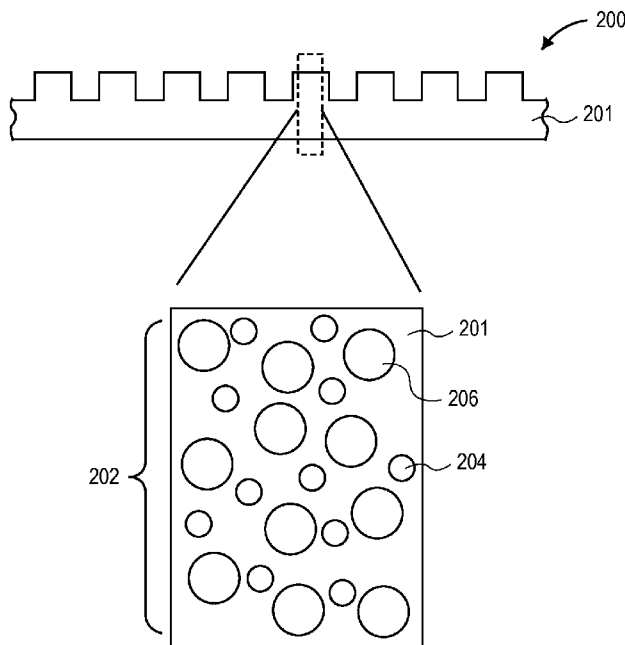


FIG. 2A

(57) Abstract: Polishing pads with multi-modal distribu-
tions of pore diameters are described. Methods of fabricat-
ing polishing pads with multi-modal distributions of pore
diameters are also described. In an example, a polishing
pad for polishing a semiconductor substrate includes a ho-
mogeneous polishing body. The homogeneous polishing
body includes a thermoset polyurethane material and a plu-
rality of closed cell pores disposed in the thermoset
polyurethane material. The plurality of closed cell pore has
a multi-modal distribution of diameters.



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